

Examiner: PHAM, LONG
Group Art Unit: 2814

Applicants : Jiro MATSUMOTO

Appl.. No. : 10/727,662

Filed : December 5, 2003

For : SEALING APPARATUS FOR SEMICONDUCTOR)
 WAFER, MOLD OF SEALING APPARATUS)
 AND SEMICONDCUTOR WAFER)

Attorney Ref.: F00ED0150-DIV

INFORMATION DISCLOSURE STATEMENT

May 31, 2006

Sir:

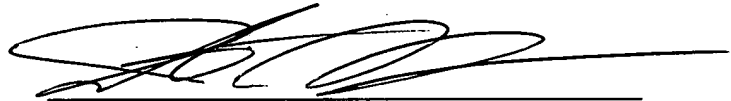
This is an information disclosure statement submitted in compliance with the timing requirements of 37 C.F.R. §1.97(c)(1).

Attached are a copy of one (1) U.S. patent publications, and eight (8) Japanese patent or utility model (Jitsuyoushinan) publications. The publications are listed on the attached Form PTO-1449. English translation or abstracts are attached thereto. These Japanese references were first cited in a communication from a Japanese patent office in the counterpart Japanese application not more than three months prior to the filing of this IDS. The Notice from Japanese Patent Office dated March 22, 2006 (mailing date) is attached hereto with English language translation.

It is noticed that since US counterpart application for one of Japanese references, which is 07-211739, has been issued in the U.S., any translation is not attached thereto.

Should any fee be needed, please charge it to our Account No. 50-0945 and advise us accordingly. Consideration of the submitted documents is respectfully requested.

Respectfully submitted,



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Attachment: Notice from Japanese Patent Office (with English)

Date: May 31, 2006

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